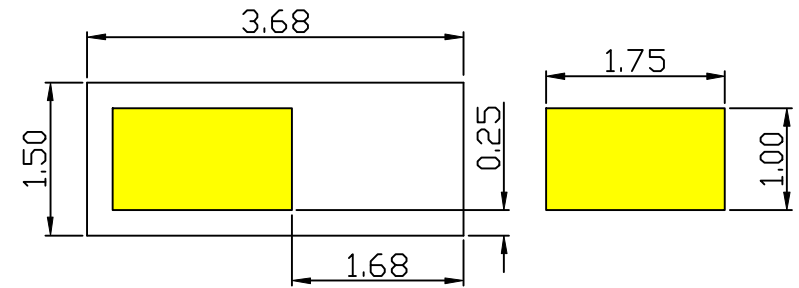
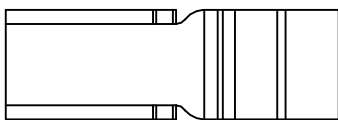
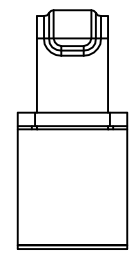
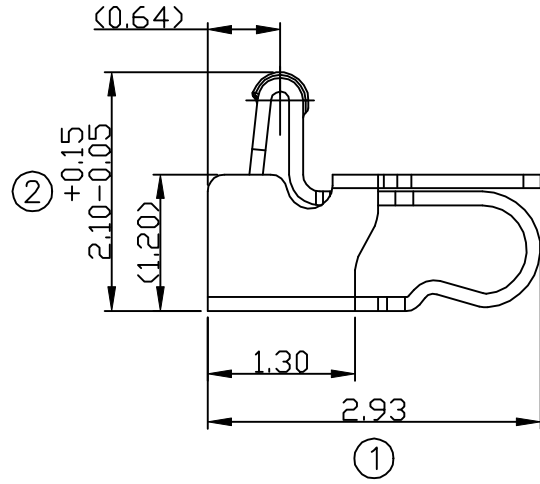
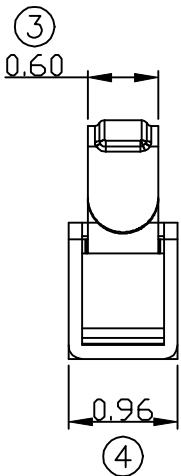
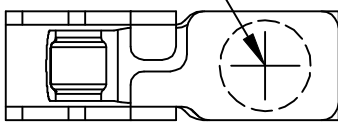
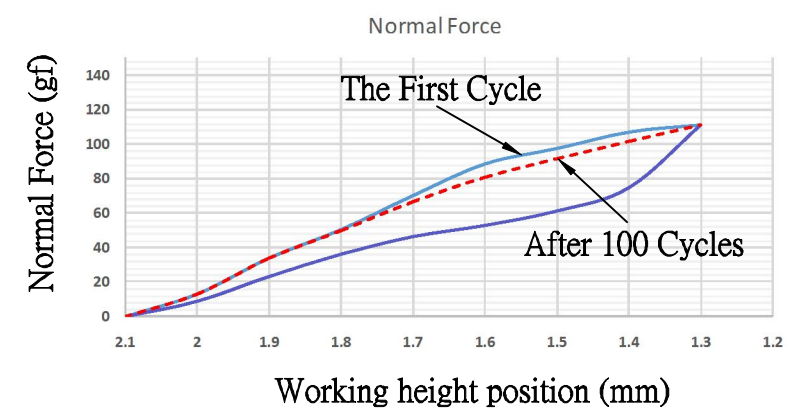


Place Area Nozzle

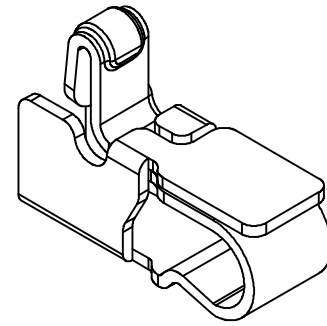


RECOMMENDED SOLDERING PCB LAYOUT
TOLERANCE(.XX±0.05)



Note:

1. Material: Titanium copper Thickness 0.12mm
2. Electroplate:
Gold Flash on contact area
Gold Flash on solder area
Nickel underplating over all
3. Electrical Characteristics:
3-1 Current Voltage: 12V
3-2 Current Rate: 3A
3-3 Contact Resistance: Normal Compression < 30mΩ
4. Working Height of Application: 1.30~1.70 mm
5. Spring Force Tolerance is ±20gf
6. Operating Temperature: -20℃~+85℃



00	12/10-'13	Design creation	
REV	Date	Description	
DRAFT	Roy Li	DATE	12/10-'13
CHECKER	Gabby Weng	DATE	12/10-'13
APPROVAL	Jacky Lin	DATE	12/10-'13
		SHEET	SCALE
		1-2	Not to scale
		UNIT	mm
		 RoHS Compatible	

TOLERANCE/CLASS			
RANGE(mm)	1	2	3
≤30	±0.10	0.15	0.20
30<- ≤120	±0.15	0.20	0.30
120<- ≤300	±0.20	0.30	0.50
300<	±0.30	0.50	0.80
ANGLES	±2.5°		

EMI STOP CORP.
 EMI STOP
 EMISTOP
 QTT-21G
 CUS P/N